

CLAIMS

What is claimed is:

1. A method of cooling a semiconductor die, comprising the steps of:
flowing fluid through micro-channels formed into the die;
5 communicating fluid from the die to a condenser arranged above the die;
cooling fluid at the condenser; and
communicating fluid from the condenser to the micro-channels.
2. A method of claim 1, the step of flowing comprising flowing fluid
through the micro-channels bounded, at least in part, by a semiconductor element
10 coupled with the die.
3. A method of claim 2, the semiconductor element comprising one of
silicon and a glass plate.
4. A method of claim 1, further comprising the step of shaping the micro-
channels for preferential fluid flow along the micro-channels.
- 15 5. A method of claim 1, the steps of communicating comprising utilizing
headers coupled with the micro-channels.
6. A method of claim 1, the step of communicating fluid from the
condenser to the micro-channels comprising utilizing gravity to force the fluid to the
condenser.